Unconfirmed Meeting Minutes:

IEEE P802.3dh Multi-Gigabit Automotive Ethernet over Plastic Optical Fiber Task Force

Plenary Meeting (Hybrid)

July 12th, 2023

Estrel Berlin, Berlin, Germany

Prepared by Kazuya Takayama

Wednesday, July 12th, 2023, 09:00 a.m.

IEEE P802.3dh Multi-Gigabit Automotive Ethernet over Plastic Optical Fiber Task Force meeting convened by Yuji Watanabe, Task Force Chair.

Attendance is listed in Appendix A

Attendance is recorded by IMAT.

Administrative Matters:

Mr. Watanabe called the meeting to order.

Mr. Watanabe reviewed General Decorum and asked if anyone from the press was present.

None responded at 09:02 a.m.

Mr. Watanabe reviewed In-Person Decorum and Teleconference Decorum.

Mr. Watanabe announced meeting registration fee and penalty for non-payment.

Mr. Watanabe displayed the agenda in Agenda dh 01 2023 7 12.pdf

Mr. Watanabe reviewed meeting agenda and asked any correction or modification needed.

No further modification/correction was asked.

No objection was made.

Motion #1:

Move to approve the agenda, Agenda dh 01 2023 7 12.pdf

Mover: Mr. Torres, Seconder: Mr. Carlson.

No discussion and no objection were made.

Agenda is approved at 09:10 a.m. by unanimous consent.

Mr. Takayama reviewed meeting minutes for May 17th Interim meeting.

(P802d3dh minutes 20230517 w attendee.pdf).

Mr. Watanabe asked any correction or modification needed.

No further correction or modification was asked.

Meeting minutes for May 17th Interim meeting was approved at 09:15 a.m.

Goals for the meeting:

- > Review the response from ISO TC22/SC32/WG10
- Following up action list
- Revise timeline according to progress of action list

Big ticket items:

- PCS/PMA/PMD
- Fiber characteristics in short length

Mr. Watanabe reviewed the access to the reflector and website, Task Force Private Area, and ground rules for the meeting.

IEEE Governance:

Mr. Watanabe reviewed the IEEE structure for standards development and the bylaws and rules by which the Task Force is governed.

IEEE Patent Policy, IEEE-SA copyright Policy:

Mr. Watanabe read aloud the patent policy slides (agenda: p.17 - p.18).

At 09:18 a.m., Mr. Watanabe made the call for potentially essential patents.

None responded.

Mr. Watanabe read aloud other guidelines and patent related information (agenda: p.19 - p.20).

Mr. Watanabe read aloud the IEEE-SA copyright policy slides (agenda: p.22 – p.23).

Mr. Watanabe read aloud the IEEE-SA participation slides (agenda: p.24 – p.26).

Project Status:

Mr. Watanabe reviewed the IEEE 802.3 Standards process and where the Task Force was in the process and the process by which we will develop the standard.

Liaisons and Communications:

Mr. Watanabe reviewed the Liaisons and Communications.

- OPEN Alliance TC7 (Multigig optical Ethernet for Automotive applications)
- Communication sent to IEC TC86A and ISO TC22/SC32 on wavelength and temperature range for automotive applications and response received

Mr. Watanabe showed the location of the approved project documents for the Task Force and reviewed the objectives for the Task Force.

Presentations:

Mr. Watanabe showed liaison letter to ISO.

Mr. Torres took chair position in order for Mr. Watanabe to make his presentation.

Presentation #1

Title: Consideration the response from ISO TC22/SC32/WG10 (Watanabe 3dh 01 2023 07 12.pdf)

Presenter: Yuji Watanabe, AGC Inc.

Mr. Watanabe showed response from ISO

Mr. Ferretti made comment about ISO standard content.

Ms. Borda asked question about the definition of "components". It led the discussion to link segment, which the TF had not defined yet.

Mr. Carlson made comment about TF's progress and possibility of PAR withdrawal.

Mr. Pardo made comment about the sample availability issue.

Action Items:

Mr. Watanabe showed To Do List (P802 3dh to-do 20230712.xlsx).

Mr. Pardo asked question about round-robin test. Mr. Watanabe provided answer.

Mr. Ferretti made comment about IEC standard development situation.

Mr. Hyakutake asked question about fiber characteristics to be measured by round-robin testing. Mr. Watanabe provided answer.

Mr. Carlson made comment about round-robin.

Mr. Watanabe showed the proposed timeline for Task Force.

Mr. Pardo made comment about the delay of project.

Mr. Carlson made comment about the TF objectives. If TF make any change to the objectives, TF needs to get approval from WG.

Mr. Torres made comment about the length of round-robin period.

Future Meetings:

September 2023 [Interim]

- September 11 -14, 2023, Campinas, Brazil

November 2023 [Plenary]

November 13 -16, 2023, Honolulu, HI

January 2024 [Interim]

- January 22 -25, 2024, Venue TBD

March 2024 [Plenary]

- March 11 -14, 2024, Denver, Colorado

Ad hoc meeting will not be scheduled due to holiday season.

Mr. Watanabe asked any other business to conduct or discussed.

Mr. Pardo commented that round-robin testing should start now by providing fiber to different company for testing to make progress by September Interim.

Mr. Carson commented that TF needs to show progress by September Interim.

The Task Force Plenary meeting was adjourned at 10:30 a.m.

(Intentionally left blank below)

Appendix A: Attendees at the IEEE P802.3dh Task Force Plenary meeting, July 12th, 2023.

Araki, Nobuyasu Yazaki Corporation Borda, Jamila Josip BMW Group Carlson, Steve HSD, Robert Bosch GmbH, Ethernovia Chang, Jae-yong Keysight Choudhury, Mabud OFS Ferretti, Vincent Corning Incorporated Gerl, Markus MD Elektronik Glanzner, Martin SEI Automotive Europe GmbH Goto, Hideki Toyota Motor Corporation Haasz, Jodi IEEE SA Harshbarger, Douglas Corning Incorporated Hirase, Hidenari AGC Hirose, Takeshi AGC Inc. Hozeska, Charles Cernitin Solutions Hyakutake, Yasuhiro Orbray Co., Ltd. Kagami, Manabu Nagoya Institute of Technology (NITech) Kaseda, Yugo Nitto Denko Corporation Kikuta, Tomohiro Orbray Co., Ltd. Koeppendoerfer, Erwin LEONI Kabel GmbH Kurashima, Kazuyoshi AGC McCellan, Brett Marvell Semiconductor, Inc. Murty, Ramana Broadcom Corporation Nilhara, Yoshihiro Fujikura Ltd. Oi, Shigehiro AGC Pardo, Carlos KDPOF Peters, Kevin Inneos Reinhard, Michael SEI Automotive Europe GmbH Ringel, Haim GM Shino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Vaisi Onter Denko Corporation Nitto Denko Corporation Nitto Denko Corporation Nitto Denko Corporation Nipara, Yoshihiro Fujikura Ltd. Oi, Shigehiro AGC Pardo, Carlos KDPOF Peters, Kevin Inneos Reinhard, Michael SEI Automotive Europe GmbH Ringel, Haim GM Shino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Kazuya Nitto Denko Corporation Torres, Luis Knowledge Development for Plastic Optical Fiber	Name	Affiliation
Carlson, Steve HSD, Robert Bosch GmbH, Ethernovia Chang, Jae-yong Keysight Choudhury, Mabud OFS Ferretti, Vincent Corning Incorporated Gerl, Markus MD Elektronik Glanzner, Martin SEI Automotive Europe GmbH Goto, Hideki Toyota Motor Corporation Haasz, Jodi IEEE SA Harshbarger, Douglas Corning Incorporated Hirase, Hidenari AGC Hirose, Takeshi AGC Inc. Hozeska, Charles Cernitin Solutions Hyakutake, Yasuhiro Orbray Co., Ltd. Kagami, Manabu Nagoya Institute of Technology (NITech) Kaseda, Yugo Nitto Denko Corporation Kikuta, Tomohiro Orbray Co., Ltd. Koeppendoerfer, Erwin LEONI Kabel GmbH Kurashima, Kazuyoshi AGC Mcclellan, Brett Marvell Semiconductor, Inc. Murty, Ramana Broadcom Corporation Nakayama, Daiki Sumitomo Electric Industries, LTD Niihara, Yoshihiro Fujikura Ltd. Oi, Shigehiro AGC Pardo, Carlos KDPOF Peters, Kevin Inneos Reinhard, Michael SEI Automotive Europe GmbH Ringel, Haim GM Shiino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Yuhei Nitto Denko Corporation Nitto Denko Corporation	Araki, Nobuyasu	Yazaki Corporation
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Peters, Kevin Inneos Reinhard, Michael SEI Automotive Europe GmbH Ringel, Haim GM Shiino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Kazuya Nitto Denko Corporation Tanaka, Yuhei Nitto Denko Corporation	Oi, Shigehiro	AGC
Reinhard, Michael SEI Automotive Europe GmbH Ringel, Haim GM Shiino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Kazuya Nitto Denko Corporation Tanaka, Yuhei Nitto Denko Corporation	Pardo, Carlos	KDPOF
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Shiino, Masato FURUKAWA ELECTRIC Steyer-Ege, Janik Bosch Takayama, Kazuya Nitto Denko Corporation Tanaka, Yuhei Nitto Denko Corporation	Reinhard, Michael	SEI Automotive Europe GmbH
Steyer-Ege, Janik Bosch Takayama, Kazuya Nitto Denko Corporation Tanaka, Yuhei Nitto Denko Corporation	Ringel, Haim	GM
Takayama, Kazuya Nitto Denko Corporation Tanaka, Yuhei Nitto Denko Corporation	Shiino, Masato	FURUKAWA ELECTRIC
Tanaka, Yuhei Nitto Denko Corporation	Steyer-Ege, Janik	Bosch
	Takayama, Kazuya	Nitto Denko Corporation
Torres, Luis Knowledge Development for Plastic Optical Fiber	Tanaka, Yuhei	Nitto Denko Corporation
	Torres, Luis	Knowledge Development for Plastic Optical Fiber

Tsujita, Yuichi	Nitto, Inc.; New Business Development Division
Tsuzaki, Nozomi	Independent
Watanabe, Yuji	AGC
Wendt, Matthias	Signify

Total: 38 attendees